PRODUCT / PROCESS CHANGE INFORMATION

| 1. PCI basic data | | |
|----------------------|---|--|
| 1.1 Company | STMicroelectronics International N.V | |
| 1.2 PCI No. | AMG/17/10092 | |
| 1.3 Title of PCI | Additional Front-end capacity in Global foundry for UA29 and UM87 product lines assembled in Carsem with new High Density frame | |
| 1.4 Product Category | See product list | |
| 1.5 Issue date | 2017-05-11 | |

| 2. PCI Team | | |
|---------------------------|-----------------------------|--|
| 2.1 Contact supplier | | |
| 2.1.1 Name | ROBERTSON HEATHER | |
| 2.1.2 Phone | +1 8475853058 | |
| 2.1.3 Email | heather.robertson@st.com | |
| 2.2 Change responsibility | | |
| 2.2.1 Product Manager | Lorenzo NASO,Antonino MOTTA | |
| 2.1.2 Marketing Manager | Marcello SAN BIAGIO | |
| 2.1.3 Quality Manager | Jean-Marc BUGNARD | |

| 3. Change | | | |
|---|--------------------|--|--|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location | |
| Transfer of a full process or process brick (process step, control plan, recipes) from one site to another site | | Front end manufacturing in ST Catania (Italy) and Global foundry (Singapore) | |

| 4. Description of change | | | |
|---|---|--|--|
| Old New | | | |
| 4.1 Description | Front-end manufacturing in ST Catania (Italy) | Front-end manufacturing in ST Catania (Italy) and Global foundry (Singapore) | |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No impact | | |

| 5. Reason / motivation for change | | |
|-----------------------------------|---|--|
| | To validate Global Foundry as additional silicon maker for product lines UA29 and UM87 with Assembly in Carsem (using new HD frame) | |
| 5.2 Customer Benefit | CAPACITY INCREASE | |

| 6. Marking of parts / traceability of change | | |
|--|--------------------|--|
| 6.1 Description | Finished good code | |

| 7. Timing / schedule | | |
|-------------------------------------|--------------|--|
| 7.1 Date of qualification results | 2017-03-01 | |
| 7.2 Intended start of delivery | 2017-06-07 | |
| 7.3 Qualification sample available? | Upon Request | |

| 8. Qualification / Validation | | | |
|---|--|---------------|-------------|
| 8.1 Description 10092 REL-6088-210-W-16-LNBH26PQR - UA29_LNBH29_UX55_to be attached to PCI .pdf | | | to PCI .pdf |
| 8.2 Qualification report and qualification results | | Issue Date | 2017-05-11 |

9. Attachments (additional documentations)

10092 Public product.pdf 10092 ADDING_GLOBAL FOUNDRY AS SECOND SOURCE_FOR BCD6S.pdf 10092 REL-6088-210-W-16-LNBH26PQR - UA29_LNBH29_UX55_to be attached to PCI .pdf

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | LNBH25LPQR | |
| | LNBH26LPQR | |
| | LNBH26PQR | |
| | ST1S06APUR | |



Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title: Additional Front-end capacity in Global foundry for UA29 and UM87 product lines assembled in Carsem with new High Density frame

PCI Reference: AMG/17/10092

Subject: Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

| LNBH26LPQR | ST1S06APUR | LNBH26PQR |
|------------|------------|-----------|
| LNBH25LPQR | | |

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